503328887 06/01/2015

EPAS ID: PAT3375505

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
Huai-Tzu Chiang	02/03/2015	
Sheng-Hao Lin	05/22/2015	
Hsin-Yu Chen	05/22/2015	
Hao-Ming Lee	05/22/2015	
Tzyy-Ming Cheng	02/03/2015	

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14726620

CORRESPONDENCE DATA

Fax Number: (703)997-4517

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Correspondent Name: WINSTON HSU **Address Line 1:** P.O.BOX 506

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ATTORNEY DOCKET NUMBER:	NAUP2438USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	06/01/2015

Total Attachments: 10 source=2262606#page1.tif source=2262606#page2.tif source=2262606#page3.tif

PATENT 503328887 REEL: 035750 FRAME: 0740

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ource=2262606#page10.tif	

PATENT REEL: 035750 FRAME: 0741

Title of Invention:

METHOD OF FABRICATING A SEMICONDUCTOR DEVICE WITH FIN-SHAPED **STRUCTURES**

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed o	on	, or
☐ PCT international application	n number	file	d on	
The above-identified application was	made or authorized to be	made by me.		
I believe that I am the original invent application.	or or an original joint inver	ntor of a claime	d invention in the)
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
In consideration of the payment by	UNITED MICROELEC	CTRONICS	having a postal	address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Pai	rk, Hsin-Chu	City 300, Tai	wan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar		ar (\$ 1.00), the	receipt of which i	s hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improven tion and, in and to, all Lett r any continuations, contin	nents which are ers Patent to b uation-in-part,	e disclosed in the e obtained for sa divisions, renewa	e iid als,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or enc n this assignment;	umbrance has	been or will be m	nade or
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	olication, said invention an ecessary or desirable to ca	d said Letters I rry out the pro	Patent and said poses thereof.	ate of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi				

Page 1 of 10

NPO#NAU-P2438-USA:0

CUST#UMCD-2014-0751

Docket No NAUP2438USA

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)		
Inventor:	Huai-Tzu Chiang	Date:	Feb. 3 15
Signature:	Huai Tzu	Chiang	

Page 2 of 10

NPO#NAU-P2438-USA:0 CUST#UMCD-2014-0751

Title of Invention:

METHOD OF FABRICATING A SEMICONDUCTOR DEVICE WITH FIN-SHAPED STRUCTURES

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☐ United States application nu	mber	filed on	, or
☐ PCT international application	number	filed on	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invente application.	or or an original joint inventor of a	claimed invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made in this dec sonment of not more than five (5)	claration is punishable) years, or both.	
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No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu City 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	l of the sum of One Dollar (\$ 1.0 d valuable consideration.	0), the receipt of which is her	reby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	id to any and all improvements w tion and, in and to, all Letters Pati any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, renewals	EE
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or encumbran this assignment;	ce has been or will be made	or
I further covenant that ASSIGNEE wi and documents relating to said inven- known and accessible to I and will te- related thereto and will promptly exec-	tion and said Letters Patent and I stify as to the same in any interfe	legal equivalents as may be rence, litigation proceeding	ts
representatives any and all papers, ir maintain, issue and enforce said appi equivalents thereof which may be ne- IN WINTNESS WHEREOF, I have he	lication, said invention and said L cessary or desirable to carry out t	etters Patent and said the proposes thereof.	f signing)
Note: An application data sheet (PTC inventive entity, must accompany this	b/SB/14 or equivalent), including r s form. Use this form for <u>each add</u>	naming the entire litional inventor.	

Page 3 of 10

Docket No NAUP2438USA

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Sheng-Hao Lin	Date:	MAY 2 2 2015	
Signature:	Shenghao Lin			

Page 4 of 10

Title of Invention:

METHOD OF FABRICATING A SEMICONDUCTOR DEVICE WITH FIN-SHAPED STRUCTURES

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The above-identified application was	s made or authorized to be made	de by me.	Maria de la companya
I believe that I am the original invent application.	or or an original joint inventor o	of a claimed invention in the	
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I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumb n this assignment;	rance has been or will be made	or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent ar stify as to the same in any inte	nd legal equivalents as may be rference, litigation proceeding	ts
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said cessary or desirable to carry o	d Letters Patent and said ut the proposes thereof.	f signing)
Note: An application data sheet (PTC inventive entity, must accompany this	o/SB/14 or equivalent), includir s form. Use this form for <u>each </u> ያ	ng naming the entire additional inventor.	

Page 5 of 10

F#NPO-P0002E-US1201 DSC0-104U000754

NPO#NAU-P2438-USA:0

REEL: 035750 FRAME: 0746

Docket No NAUP2438USA

Page 6 of 10

Title of Invention:

METHOD OF FABRICATING A SEMICONDUCTOR DEVICE WITH FIN-SHAPED STRUCTURES

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed	on	, or
☐ PCT international application	number	file	ed on	**
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I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, an	d to any and all improvion and, in and to, all L any continuations, cor	rements which are letters Patent to be atinuation-in-part	e disclosed in the e obtained for said divisions, renewals	JEE
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or e this assignment;	ncumbrance has	been or will be made	or
I further covenant that ASSIGNEE wi and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	tion and said Letters P stify as to the same in a	atent and legal eq anv interference. I	uivalents as may be	zts
representatives any and all papers, ir maintain, issue and enforce said appl equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	ication, said invention cessary or desirable to	and said Letters F carry out the prop	Patent and said poses thereof.	of signing)
Note: An application data sheet (PTO nventive entity, must accompany this	/SB/14 or equivalent), form. Use this form fo	including naming r <u>each additional</u>	the entire inventor.	

Page 7 of 10

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Hao-Ming Lee	Date:	MAY	22	2015	
Haothing Lee					
	Hao-Ming Lee	Hao-Ming Lee Date:	Hao-Ming Lee Date: MAY	Hao-Ming Lee Date: MAY 2.2	Hao-Ming Lee Date: MAY 2 2 2015

Page 8 of 10

Title of Invention:

METHOD OF FABRICATING A SEMICONDUCTOR DEVICE WITH FIN-SHAPED STRUCTURES

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l hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbrar		or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be rence, litigation proceeding	ts
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NPO#NAU-P2438-USA:0 CUST#UMCD-2014-0751

F#NPO-P0002E-US1201 DSC0-104U000754

PATENT REEL: 035750 FRAME: 0750 LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Tzyy-Ming Cheng

Date?

Signature:

Page 10 of 10

F#NPO-P0002E-US1201 DSC0-104U000754

RECORDED: 06/01/2015

NPO#NAU-P2438-USA:0

CUST#UMCD-2014-0751

PATENT REEL: 035750 FRAME: 0751